

Doc. No.: 2223002 Issue date: March 1, 2023

> Akihiro Hikasa General Manager

High Power Device Division Power Discrete Headquarters ROHM Co., Ltd.

Notification of Product/Process Change

This is an announcement of change(s) to the process of the products currently supplied by ROHM Co., Ltd.

We request your acknowledgement of the receipt of this notification within the given period.

Please provide your your reply by October 1, 2023

cacc p. ca	5 / 5 di. / 5 di 5 p . / 5 / 5 di 5 di . 1 / 2 5 2 5					
Title of change	IGBT RGT-Series TO-252 assembly factory addition					
Manufacturer part number			Customer part number			
Affected product(s)	RGT8BM65DTL					
	Now		After			
Detailed description of change	Assembly factory : ROHM Korea Corporation		Assembly factory : ROHM Korea Corporation Sub contract assembly factory (GEM Electoronics (Hefei) Co.,Ltd)			
Reason for change	In order to increase the production capacity and secure a stable product supply.					
Anticipated impact on quality	There is no difference and influence in electrical charecteristics and reliability level. (report in the attached file)					
Identification of change	Changed products can be identified by part number and marking.					
Planned first ship o	Planned first ship date : March 1, 2024 Sample available schedule : March 1, 2023					
Attachements (dat	ta, report) yes 4M 22	23002_4M	E RIbl 2223002-3_RIbl			
Comments	*Samples : Within 3 weeks from request					
		Repl	v date			
Customer reply 1. Approved. 2. Accepted with conditions.						
Condition for appi	oval / reason for rejection					
Comments						
Customer compan						
Customer signatur	nent					
Customer signature Departm			nent			



Only Accessible by XXXXX and ROHM



Electronics for the Future

No.2223002

IGBT RGT-Series TO-252 assembly factory addition PCN Details

Jan. 2023 High power device div. Discrete product development dept.

© ROHM Co., Ltd.

Contents



- Overview
- Outline of factory
- Outline of TO-252 OSAT* Partner
- Affected product and changing points
- Additional approval OSAT

*OSAT: Outsourced Semiconductor Assembly and Test (Implementation of back-end processes by contractor)

© ROHM Co., Ltd.

Overview



[Additional approval OSAT (Outsourced Semiconductor Assembly and Test)]

Situation and Purpose

Demand for IGBT (Insulated Gate Bipolar Transistor) is expected to increase due to the increase of demand for power devices.

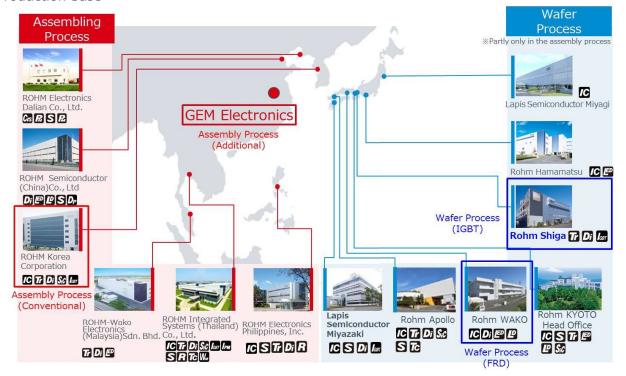
In order to respond to the recent rapid increase in demand for power devices, ROHM will utilize the capacity of **our OSAT partner**.

This also act as our Business Continuity Planning (BCP) to mitigate the risks in the event of a disaster.

Outline of factory



Production base



© ROHM Co., Ltd.

Outline of TO-252 OSAT Partner



■Overview

Category	Content				
Headquarters	Headquarters GEM Electronics Co., Ltd. (Taipei, Taiwan)				
TO-252 Production Location	GEM Electronics Co., Ltd. (Hefei Factory/Anhui, China)				
Capacity	4000Mpcs/year	4 35			
•Advanced Power Packages •Multi Chip Modules Technology •Leaded: J-lead Wide-body •Leadless: PQFN5x6, PQFN3.3x3.3 •Bond-wireless: Flip chip, Cu clip, Al ribbon		Anha. Androp. Senting. Kanhaiung. Taiwan			
Computer, Smartphone, Tablet PC LEC/Plasma Display Froducts Products Industrial Machinery, Solar Applications, Wind-power Generators Hybrid EV					
Quality Certificates	ISO14001:2015, ISO 9001:2008, IATF 16949:2016				
Number of Employees	ees Approximately 1600 (470 engineers)				
Hefei Factory Location 77 Jinxiu Ave, Shushan Qu, Hefei Shi, Anhui Sheng, China					

Contents



- Overview
- Outline of factory
- Outline of TO-252 OSAT* Partner
- Affected product and changing points
- Additional approval OSAT

*OSAT: Outsourced Semiconductor Assembly and Test (Implementation of back-end processes by contractor)

© ROHM Co., Ltd.

Affected product and changing points



ROHM Korea Corporation (ROHM Korea will be used from here on) GEM Electronics (Hefei) Co., Ltd (GEM will be used from here on)

Product	Assembly process	
Conventional product	ROHM Korea (Internal manufacturing site)	
Additional product	GEM (OSAT)	

ROHM Korea	GEM	
RGT8BM65DTL	RGT8BM65DGTL1	

(*)The object of this time PCN is above RGT8BM65DTL only.

< Conventional product > product name: RGT8BM65D TL

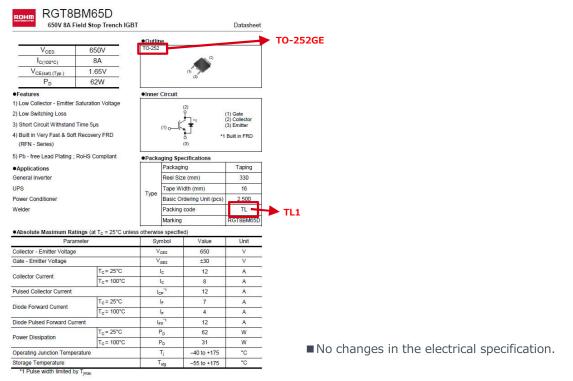
< Additional product >

product name: RGT8BM65D G TL1

Verification of Datasheet Changes

www.rohm.com © 2020 ROHM Co., Ltd. All rights reserved.





2020.7 - Rev.C

Contents



- Overview
- Outline of factory
- Outline of TO-252 OSAT* Partner
- Affected product and changing points
- Additional approval OSAT

*OSAT: Outsourced Semiconductor Assembly and Test (Implementation of back-end processes by contractor)

© ROHM Co., Ltd.

Assembly Process changing point (4M comparison)

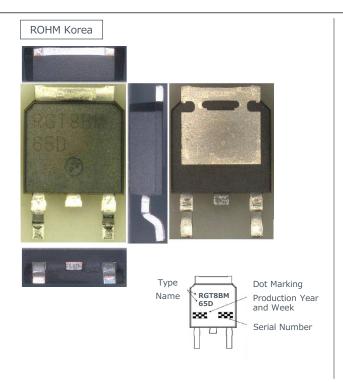


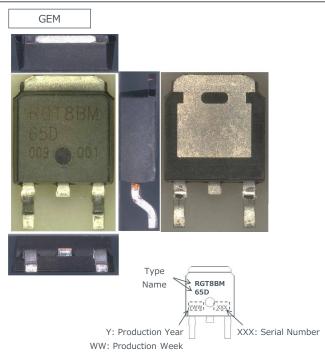
ROHM Korea Corporation GEM Electronics (Hefei) Co., Ltd

			Assembly Factory				
		Target	Conventional	Additional	Concerns	Verification	Judgement
			ROHM Korea	GEM			
	Man	Operator	License system	License system	Operational skills	No difference in learning level and skill	OK
4 M	Machine	Production equipment	Equipment owned by ROHM	Equipment owned by GEM	product quality		OK
	Material	Process material	Material used by ROHM	Material used by GEM	product quality	Process changing point verification	
		Wafer	*Wafer provided by ROHM				[
	Method	Method	Operation standards of ROHM	Operation standards of GEM	product quality		

TO-252 Package Outline and Marking comparison



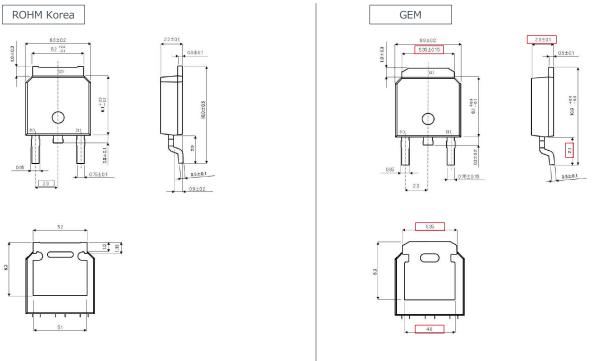




© ROHM Co., Ltd. P. 10

TO-252 External dimensions comparison





© ROHM Co., Ltd.

TO-252 Material for Assembly Comparison



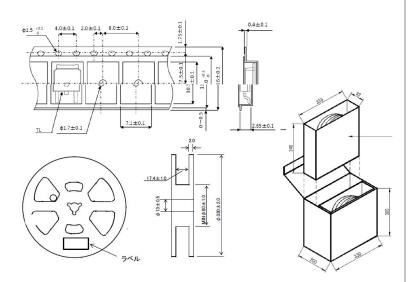
■ Material

Cata mana	конм	Korea	GEM		
Category	Model (Specs)	Supplier	Model (Specs)	Supplier	
Frame	Cu Alloy	Supplier A	Cu Alloy (Only the shape is different)	Supplier B	
Solder	Pb-Sn-Ag	Supplier C	Pb-Sn-Ag (Same specs)	Supplier C	
Wire	AI	Supplier D	AI (Same specs)	Supplier E	
Resin	Epoxy Resin	Supplier F	Epoxy Resin (Same material group)	Supplier F	
Terminal Plating	Sn100%	-	Sn100% (Same Specs)	-	

TO-252 Inner Box Outer Box Taping comparison

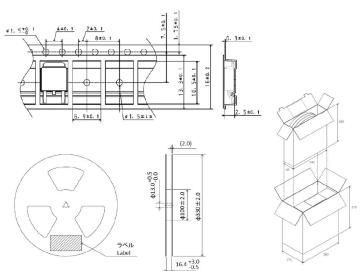


■TO-252 Korea Code: TL



Outer box: 20K pcs (2500 pcs per reel \times 8 reels) Carrier tape material: polystyrene

■TO-252 GEM Code: TL1



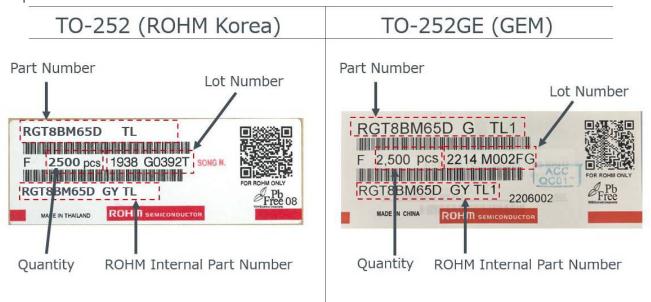
Outer box: 20K pcs (2500 pcs per reel × 8 reels) Carrier tape material: polystyrene

© ROHM Co., Ltd. P. 13

TO-252 Label specifications comparison



■ Label Specifications





Electronics for the Future

ROHM Co., Ltd. © ROHM Co., Ltd.

Public (External) PN Replacement RGT8BM65DTL RGT8BM65DGTL1